L Number	Hits	Search Text	DB	Time stamp
1	4	(("5170009") or ("6245259")).PN.	USPAT;	2003/01/21 13:13
1	•	((31,000) / 32 (32,000)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
_	3	coat\$4 with (chip IC die LED) and	USPĀT;	2003/01/14 13:33
]	١	(amorphous adj fluororesin)	US-PGPUB;	
		(amo provide the grant of the g	EPO; JPO;	
	ļ		DERWENT;	1
			IBM_TDB	
\ _	71	amorphous adj fluororesin	USPAT;	2003/01/14 13:33
			US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	2003/01/14 13:34
-	6	\ \ \ \ \ \ \ \ \ \	USPAT;	2003/01/14 13.54
		die LED)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		1 (alia dia IC IED)	IBM_TDB USPAT;	2003/01/16 15:39
-	71		US-PGPUB;	2003/01/10 13.33
		and coat\$4	EPO; JPO;	
			DERWENT;	
			IBM TDB	
		257/294.ccls. and (chip die IC LED)	USPAT;	2003/01/14 13:40
-	61	ZDI/ZB4.CCIS. and (Chip die ic bbb)	US-PGPUB;	
Ì			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
	354	257/290-292.ccls. and (chip die IC LED)	USPAT;	2003/01/14 13:45
-	334	23//290-292:0013: and (entp die 10 111)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	4	(("6051848") or ("6274890")).PN.	USPAT;	2003/01/14 13:47
	•		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (01 (14 12 51
-	2027	257/88,91,94-100.ccls. and (chip die LED	USPAT;	2003/01/14 13:51
		IC)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		1 Ashin die IED	IBM TDB	2003/01/14 13:50
-	3	257/88,91,94-100.ccls. and (chip die LED	USPAT; US-PGPUB;	2003,01,14 13.30
1		IC) and ((amorphous adj fluororesin) PTFE)	EPO; JPO;	
1			DERWENT;	
1			IBM TDB	
		257/88,91,94-100.ccls. and (chip die LED	USPAT;	2003/01/14 13:52
-	2027		US-PGPUB;	
	-	IC)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	284	257/88,91,94-100.ccls. and (chip die LED	USPAT;	2003/01/14 16:00
-	284	IC) and lead and resin	US-PGPUB;	
		To, and Toda and Tooth	EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	
1_	2408	257/666,690,692-693,787-788,790.ccls. and	USPĀT;	2003/01/14 16:13
'	2300	(chip die LED IC) and lead and resin	US-PGPUB;	
		,- •	EPO; JPO;	
1	1		DERWENT;	
			IBM_TDB	0000/01/14 16 51
-	423	257/666,690,692-693,787-788,790.ccls. and	USPAT;	2003/01/14 16:51
1	1	(chip die LED IC) with coat\$4 and lead and	US-PGPUB;	
1		resin	EPO; JPO;	
			DERWENT;	
			IBM TDB	

T- T	1	(257/\$.ccls. 438/\$.ccls.) and (amorphous	USPAT;	2003/01/14 16:53
1		adj fluororesin) with (PTFE	US-PGPUB;	
1		polytetrafluoroethylene)	EPO; JPO;	
			DERWENT;	
		the state of the s	IBM_TDB USPAT;	2003/01/16 15:04
-	3	(amorphous adj fluororesin) with (PTFE	US-PGPUB;	2003/01/10 13.04
		polytetrafluoroethylene)	EPO; JPO;	1
			DERWENT;	
			IBM TDB	
	0.600	438/612-614,108,118.ccls. and (bump ball)	USPĀT;	2003/01/15 14:05
-	2620	438/612-614,108,116.CCIS. and (bump ball)	US-PGPUB;	
[l		EPO; JPO;	
			DERWENT;	
	Ì		IBM TDB	
1	170	438/612-614,108,118.ccls. and (bump ball)	USPAT;	2003/01/15 14:13
-	170	with (\$1m micrometer m)	US-PGPUB;	
]		WICH (VIM MISISMOSSI)	EPO; JPO;	
!			DERWENT;	
			IBM_TDB	
_	138	438/612-614,108,118.ccls. and (bump ball)	USPAT;	2003/01/15 14:28
	130	with pitch and (\$1m micrometer m)	US-PGPUB;	
		•	EPO; JPO;	
	,		DERWENT;	
			IBM_TDB	
-	205	438/612-614,108,118.ccls. and (bump ball)	USPAT;	2003/01/15 14:16
		with (pitch spac\$4) and (\$1m micrometer m)	US-PGPUB;	
		<u> </u>	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2003/01/15 15:06
-	1107	438/612-614,108,118.ccls. and (bump ball)	USPAT;	2003/01/13 13:00
1		with (layer adher\$4)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
			USPAT;	2003/01/15 14:34
-	0	("59373210").PN.	US-PGPUB;	2003/01/13 11.51
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
	2	("5937320").PN.	USPAT;	2003/01/15 14:34
_	2	(~593/320).FN.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	("5162257" "5391514" "5470787"	USPĀT	2003/01/15 14:35
_	1	"5634268").PN.		
_	17	5937320.URPN.	USPAT	2003/01/15 14:35
_	502	1	USPAT;	2003/01/15 15:08
		(layer adher\$4)	US-PGPUB;	
			EPO; JPO;	
		1	DERWENT;	
			IBM_TDB	0000/01/15 15:00
-	73	257/733,778-779.ccls. and (bump ball) with	USPAT;	2003/01/15 15:08
Ì		(layer adher\$4) and (bond adj pad)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2003/01/15 15:09
-	667	1 ' •	USPAT;	5003/01/12 12:08
	ļ	adj pad)	US-PGPUB;	
	1		EPO; JPO;	1
1			DERWENT;	
			IBM_TDB	2003/01/15 15:09
-	219		USPAT;	2003/01/13 13:09
		and (bond adj pad)	US-PGPUB;	
			EPO; JPO;	1
:			DERWENT;	
İ	}		IBM TDB	

			USPAT;	2003/01/15 15:30
_	3	(bump ball) with pitch with (layer	US-PGPUB;	2003, 01, 10
		adher\$4) and (bond adj pad)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	1,220	adher\$4 with (protective passivation) with	USPAT;	2003/01/15 15:32
-	1372	adners4 with (protective passivation, with	US-PGPUB;	•
		(barrier metal)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
		adher\$4 with ((protective passivation) adj	USPAT;	2003/01/15 15:33
-	281	layer) with (barrier metal)	US-PGPUB;	
i	ì	layer) with (ballier metal)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	36	adher\$4 with ((protective passivation) adj	USPAT;	2003/01/15 16:46
-	36	layer) with (barrier metal) and (bump	US-PGPUB;	
			EPO; JPO;	i i
		ball)	DERWENT;	1
			IBM TDB	1
		("6465582").PN.	USPĀT;	2003/01/16 13:10
-	2	(0403302).EN.	US-PGPUB;	
İ			EPO; JPO;	
}			DERWENT;	
İ			IBM TDB	
1	_	(#6245250#) PN	USPAT;	2003/01/16 15:04
-	2	("6245259").PN.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	_	large conditions and film)	USPAT;	2003/01/16 15:43
-	0	257/290-294.ccls. and (coating adj film)	US-PGPUB;	
		near2 thickness with m	EPO; JPO;	
			DERWENT;	
1			IBM TDB	
	_		USPAT;	2003/01/16 15:44
-	0	257/290-294.ccls. and (coating adj film)	US-PGPUB;	2000, 02, 21
		with thickness with (m micrometer)	EPO; JPO;	
	1		DERWENT;	
1			IBM TDB	
	1	(chip die IC LED) and (coating adj film)	USPAT;	2003/01/16 20:14
-	41	with thickness with (m micrometer)	US-PGPUB;	
		with thickness with (m micrometer)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
		() : die TC IED load wire) and (coating	USPĀT;	2003/01/16 15:53
-	11234	(chip die IC LED lead wire) and (coating	US-PGPUB;	
ļ		adj film)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
		(chip die IC LED lead wire) with (coating	USPAT;	2003/01/16 15:54
-	1987	(Cuib die ic PPD lead wite) wien (courting	US-PGPUB;	
		adj film)	EPO; JPO;	
1			DERWENT;	
			IBM TDB	
		(2) and with (southing add film)	USPAT;	2003/01/16 15:54
-	1324	(lead wire) with (coating adj film)	US-PGPUB;	
i	i		EPO; JPO;	
			DERWENT;	
			IBM TDB	1
1			USPAT;	2003/01/16 16:21
-	319	(lead wire) near2 (coating adj film)	US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
1			IBM TDB	
		de la company de	USPAT;	2003/01/16 16:02
1 -	1	(lead wire) near2 (coating adj film) and	US-PGPUB;	2000,02,20
		(amorphous adj fluororesin)	EPO; JPO;	
			DERWENT;	
1	1	•	IBM TDB	1
1				L.

			USPAT;	2003/01/16 16:03
-	17	(lead wire) and (amorphous adj	US-PGPUB;	2003,01,10 10.03
		fluororesin)	EPO; JPO;	
i			DERWENT;	
1				•
			IBM_TDB	2003/01/16 16:23
-	730	(lead wire) near2 ((coating adj film)	USPAT;	2003/01/10 10.23
]		(plating adj layer))	US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
	1		IBM_TDB	2003/01/16 16:28
1 –	47	lead\$4 near4 wir\$4 near2 ((coating adj	USPAT;	2003/01/16 16:26
	1	film) (plating adj layer))	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (01 (16 16 25
1 _	405	lead\$4 and wir\$4 near5 ((coating adj film)	USPAT;	2003/01/16 16:35
		(plating adj layer))	US-PGPUB;	ļ i
			EPO; JPO;	
}			DERWENT;	
}			IBM_TDB	
1_	1 1	lead\$4 and wir\$4 near5 ((coating adj film)	USPAT;	2003/01/16 16:52
	_	(plating adj layer)) and (amorphous adj	US-PGPUB;	
i		fluororesin)	EPO; JPO;	
1			DERWENT;	
			IBM TDB	
\ _	26	(coating adj (film layer)) near2	USPAT;	2003/01/21 13:12
	20	(micrometer um)	US-PGPUB;	
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	("5221859").PN.	USPAT;	2003/01/16 20:25
	_	, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	

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